

## Title (en)

Water-soluble copper, copper alloys and non-ferrous metals intermediate cold and hot rolling composition

## Title (de)

Wasserlösliche Zusammensetzung für Kalt- und Warmwalzen von Kupfer, Kupferlegierungen und Nichteisen-Metalzwischenprodukten

## Title (fr)

Composition soluble dans l'eau pour le laminage à froid et à chaud de cuivre, d'alliages de cuivre et de produits intermédiaires non-ferreux

## Publication

**EP 1123971 A1 20010816 (EN)**

## Application

**EP 00400348 A 20000208**

## Priority

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## Abstract (en)

The present invention relates to a water-soluble copper, copper alloys and non-ferrous metals intermediate cold and hot rolling composition comprising a base stock oil and, based on the total weight of the composition : from 1 to 80% by weight of a combination of a monoester of a fatty acid with a polyol and a tetraester of a fatty acid with pentaerythritol; the weight monoester : tetraester ratio of said combination ranging from 1:20 to 10:1; and from 0.02 to 2% by weight of an azole derivative. The invention also relates to an oil-in-water emulsion, an intermediate cold rolling process, a hot rolling process and the use of the oil-in-water emulsion in an intermediate cold or hot rolling process. <IMAGE>

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## Citation (search report)

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- [A] DATABASE WPI Section Ch Week 197412, Derwent World Patents Index; Class H07, AN 1974-22038V, XP002141302
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